

REMARKS/ARGUMENTS

The Office Action mailed October 3, 2006 has been received and reviewed. Claims 1 through 19 are currently pending in the application. Claims 1 through 4 are withdrawn from consideration as being drawn to a non-elected invention and have been canceled. Claims 5 through 19 stand rejected. Applicant has amended claims 5 and 6, and respectfully requests reconsideration of the application as amended herein.

Restriction Requirement

Applicant herein acknowledges the restriction requirement in the above-referenced application. Claims 1 through 19 are currently pending in the application. The Office has identified the following groups of claims as being drawn to separate inventions:

Invention I – Claims 1-4, drawn to an apparatus for processing electronic component assemblies, classified in class 425, subclass 174.4; and

Invention II – Claims 5-19, drawn to a process of processing electronic component assemblies, classified in class 264, subclass 401.

Applicant affirms the election of the claims of Invention II, claims 5 through 19, without traverse.

Information Disclosure Statement

Applicant notes the filing of an Information Disclosure Statement herein on September 26, 2003 and notes that no copy of the Form PTO-1449 was returned with the outstanding Office Action. Applicant respectfully requests that the information cited on the Form PTO-1449 (which is the same as that of record to that date in the parent application hereto) be made of record herein.

Preliminary Amendment

Applicant's undersigned attorney notes the filing herein of a Preliminary Amendment on January 7, 2004, which filing was not acknowledged in the outstanding Office Action. Should the Preliminary Amendment have failed for some reason to have been entered in the Office file, Applicant's undersigned attorney will be happy to have a true copy thereof hand-delivered to the Examiner.

Double Patenting Rejections

Double Patenting Rejection Based on U.S. Patent No. 6,549,821 B1

Claims 5 through 19 stand rejected under the judicially created doctrine of obviousness-type double patenting for reciting subject matter that is allegedly unpatentable over the subject matter recited in claims 1, 8, and 9 of U.S. Patent No. 6,549,821 B1, claims 1, 4 through 7, 14, and 15 of U.S. Patent No. 6,593,171 B2, claims 1, 5 through 8, 15, and 16 of U.S. Patent No. 6,890,801 B2, and claims 1, 5 through 7, 11, and 12 of U.S. Patent No. 6,909,929 B2.

An obviousness-type double patenting rejection is appropriate where the subject matter recited in a claim is merely an obvious variation of the invention recited in a claim of an issued or patent or pending patent application. M.P.E.P. § 804.

A double patenting rejection of the obviousness-type is 'analogous to [a failure to meet] the nonobviousness requirement of 35 U.S.C. 103' except that the patent principally underlying the double patenting rejection is not considered prior art. *In re Braithwaite*, 379 F.2d 594, 154 USPQ 29 (CCPA 1967). Therefore, any analysis employed in an obviousness-type double patenting rejection parallels the guidelines for analysis of a 35 U.S.C. 103 obviousness determination. *In re Braat*, 937 F.2d 589, 19 USPQ2d 1289 (Fed. Cir. 1991); *In re Longi*, 759 F.2d 887, 225 USPQ 645 (Fed. Cir. 1985). M.P.E.P. § 804.

It is respectfully submitted that the obviousness-type double patenting rejections of claims 5-19 are inappropriate.

U.S. Patent 6,549,821

Claims 1, 8 and 9 of U.S. Patent 6,549,821 are directed to a method of packaging a semiconductor die.

It is respectfully submitted that the subject matter to which claims 1, 8 and 9 of U.S. Patent 6,549,821 is directed does not support a *prima facie* case of obviousness against any of claims 5 through 19 of the above-referenced application. In particular, it is respectfully submitted that none of claims 1, 8 and 9 of U.S. Patent 6,549,821 recites (or teaches or suggests) securing a plurality of electronic component assemblies to a platen assembly in fixed positions with one side of each of the plurality of electronic component assemblies including *electronic components exposed through the platen assembly*, as recited in independent claim 5 of the above-referenced application, or adhering a plurality of electronic components in fixed positions to one side of a film supported by a frame member and securing the frame member to a platform within a stereolithography apparatus, as recited in independent claim 11 of the above-referenced application. Moreover, it is respectfully submitted that claims 1, 8 and 9 of U.S. Patent 6,549,821 would not provide one of ordinary skill in the art with any motivation to modify the methods thereof to include electronic components exposed through a platen assembly or adhering electronic components to a film supported by a frame member and securing the frame member to a platform.

Therefore, it is respectfully submitted that the subject matter recited in independent claims 5 and 11 of the above-referenced application is allowable over the subject matter to which claims 1, 8 and 9 of U.S. Patent 6,549,821 is directed.

Claims 6-10 are each allowable, among other reasons for depending directly or indirectly from independent claim 5, which is allowable.

Each of claims 12-19 is allowable, among other reasons, for depending directly from independent claim 11, which is allowable.

U.S. Patent No. 6,593,171

Claims 5 through 19 stand rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 1, 4 through 7, 14, and 15 of U.S. Patent No. 6,593,171 B2

Claims 1, 4 through 7, 14, and 15 of U.S. Patent No. 6,593,171 are directed to a method of fabricating a substantially hermetic package.

It is respectfully submitted that the subject matter to which claims 1, 4 through 7, 14, and 15 of U.S. Patent No. 6,593,171 is directed does not support a *prima facie* case of obviousness against any of claims 5 through 19 of the above-referenced application. In particular, it is respectfully submitted that none of claims 1, 4 through 7, 14, and 15 of U.S. Patent No. 6,593,171 recites (or teaches or suggests) securing a plurality of electronic component assemblies to a platen assembly in fixed positions with one side of each of the plurality of electronic component assemblies including *electronic components exposed through the platen assembly*, as recited in independent claim 5 of the above-referenced application, or adhering a plurality of electronic components in fixed positions to one side of a film supported by a frame member and securing the frame member to a platform within a stereolithography apparatus, as recited in independent claim 11 of the above-referenced application. Moreover, it is respectfully submitted that claims 1, 4 through 7, 14, and 15 of U.S. Patent No. 6,593,171 would not provide one of ordinary skill in the art with any motivation to modify the methods thereof to include electronic components exposed through a platen assembly or adhering electronic components to a film supported by a frame member and securing the frame member to a platform.

Therefore, it is respectfully submitted that the subject matter recited in independent claims 5 and 11 of the above-referenced application is allowable over the subject matter to which claims 1, 4 through 7, 14, and 15 of U.S. Patent No. 6,593,171 is directed.

Claims 6-10 are each allowable, among other reasons for depending directly or indirectly from independent claim 5, which is allowable.

Each of claims 12-19 is allowable, among other reasons, for depending directly from independent claim 11, which is allowable.

U.S. Patent No. 6,890,801

Claims 5 through 19 stand rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 1, 5 through 8, 15, and 16 of U.S. Patent No. 6,890,801 B2.

Claims 1, 5 through 8, 15, and 16 of U.S. Patent No. 6,890,801 are directed to a method of fabricating a substantially hermetic package.

It is respectfully submitted that the subject matter to which claims 1, 5 through 8, 15, and 16 of U.S. Patent No. 6,890,801 is directed does not support a *prima facie* case of obviousness against any of claims 5 through 19 of the above-referenced application. In particular, it is respectfully submitted that none of claims 1, 5 through 8, 15, and 16 of U.S. Patent No. 6,890,801 recites (or teaches or suggests) securing a plurality of electronic component assemblies to a platen assembly in fixed positions with one side of each of the plurality of electronic component assemblies including *electronic components exposed through the platen assembly*, as recited in independent claim 5 of the above-referenced application, or adhering a plurality of electronic components in fixed positions to one side of a film supported by a frame member and securing the frame member to a platform within a stereolithography apparatus, as recited in independent claim 11 of the above-referenced application. Moreover, it is respectfully submitted that claims 1, 5 through 8, 15, and 16 of U.S. Patent No. 6,890,801 would not provide one of ordinary skill in the art with any motivation to modify the methods thereof to include electronic components exposed through a platen assembly or adhering electronic components to a film supported by a frame member and securing the frame member to a platform.

Therefore, it is respectfully submitted that the subject matter recited in independent claims 5 and 11 of the above-referenced application is allowable over the subject matter to which claims 1, 5 through 8, 15, and 16 of U.S. Patent No. 6,890,801 is directed.

Claims 6-10 are each allowable, among other reasons for depending directly or indirectly from independent claim 5, which is allowable.

Each of claims 12-19 is allowable, among other reasons, for depending directly from independent claim 11, which is allowable.

U.S. Patent No. 6,909,929

Claims 5 through 19 stand rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 1, 5 through 7, 11, and 12 of U.S. Patent No. 6,909,929 B2.

Claims 1, 5 through 7, 11, and 12 of U.S. Patent No. 6,909,929 are directed to a method of fabrication of articles:

It is respectfully submitted that the subject matter to which claims 1, 5 through 7, 11, and 12 of U.S. Patent No. 6,909,929 is directed does not support a *prima facie* case of obviousness against any of claims 5 through 19 of the above-referenced application. In particular, it is respectfully submitted that none of claims 1, 5 through 7, 11, and 12 of U.S. Patent No. 6,909,929 recites (or teaches or suggests) securing a plurality of electronic component assemblies to a platen assembly in fixed positions with one side of each of the plurality of electronic component assemblies including *electronic components exposed through the platen assembly*, as recited in independent claim 5 of the above-referenced application, or adhering a plurality of electronic components in fixed positions to one side of a film supported by a frame member and securing the frame member to a platform within a stereolithography apparatus, as recited in independent claim 11 of the above-referenced application. Moreover, it is respectfully submitted that claims 1, 5 through 7, 11, and 12 of U.S. Patent No. 6,909,929 would not provide one of ordinary skill in the art with any motivation to modify the methods thereof to include electronic components exposed through a platen assembly or adhering electronic components to a film supported by a frame member and securing the frame member to a platform.

Therefore, it is respectfully submitted that the subject matter recited in independent claims 5 and 11 of the above-referenced application is allowable over the subject matter to which claims 1, 5 through 7, 11, and 12 of U.S. Patent No. 6,909,929 is directed.

Claims 6-10 are each allowable, among other reasons for depending directly or indirectly from independent claim 5, which is allowable.

Each of claims 12-19 is allowable, among other reasons, for depending directly from independent claim 11, which is allowable.

35 U.S.C. § 102 Anticipation Rejections

Anticipation Rejection Based on U.S. Patent No. 6,549,821 B1 to Farnworth et al.

Claims 5 through 19 stand rejected under 35 U.S.C. § 102(e) as being anticipated by Farnworth et al. (U.S. Patent No. 6,549,821 B1). Applicant respectfully traverses this rejection, as hereinafter set forth.

A claim is anticipated only if each and every element as set forth in the claim is found, either expressly or inherently described, in a single prior art reference. *Verdegaal Brothers v. Union Oil Co. of California*, 2 USPQ2d 1051, 1053 (Fed. Cir. 1987). The identical invention must be shown in as complete detail as is contained in the claim. *Richardson v. Suzuki Motor Co.*, 9 USPQ2d 1913, 1920 (Fed. Cir. 1989).

The 35 U.S.C. § 102(e) anticipation rejections of claims 5 through 19 are improper because Farnworth fails to describe each and every element as set forth in claims 5 through 9.

Farnworth describes a stereolithographic method for applying packaging material to workpieces. A die 100 may be placed on a sheet of material 120 on surface 30 of platform 20 with which liquid material 16 is compatible. (FIG. 4, col. 12 lines 18-21). Alternatively, a package bottom 110 may be built in one or more layers 60 on the surface 30 of platform 20 or on a precisely-dimensioned carrier sheet 124. (Col. 12, lines 33-41). Another approach may be suitable for lead frame-mounted dice 100 uses a lead frame strip 130 carrying dice 100. (Col. 12, lines 45-50, FIGS. 6A and 6B) A plurality of dice 100 secured and electrically connected to a carrier substrate 200 to create a multi-chip module 1000 may be encapsulated in place. FIG. 7 depicts the carrier substrate 200 on the surface 30 of platform 20. (Col. 13, lines 28-36)

Claim 5, as amended herein, recites a “method of processing electronic component assemblies, comprising: securing a plurality of electronic component assemblies to a platen assembly in fixed positions with one side of each of the plurality of electronic component assemblies including electronic components exposed through the platen assembly; securing the platen assembly to a platform within a stereolithography apparatus with the exposed electronic components on the one side of each of the plurality of electronic component assemblies facing upward; forming at least one stereolithographic structure adjacent each of the exposed electronic components on the one side of each of the plurality of electronic component assemblies; and removing the platen assembly from the stereolithography apparatus.”

Farnworth fails to disclose securing electronic component assemblies to a platen assembly with one side of each of the plurality of electronic component assemblies *exposed through* the platen assembly. Rather, Farnworth discloses a die positioned on a sheet of material of a platform.

Therefore, it is respectfully submitted that the references fail to disclose each and every element of claim 5. Accordingly, it is respectfully submitted that the rejection to claim 5 should be withdrawn.

Claims 6-10 are each allowable, among other reasons for depending directly or indirectly from independent claim 5, which is allowable.

Independent claim 11 recites a “method of processing electronic components, comprising: adhering a plurality of electronic components in fixed positions to one side of a film supported by a frame member; securing the frame member to a platform within a stereolithography apparatus with the plurality of electronic components adhered to the one side of the film facing upward; forming at least one stereolithographic structure adjacent each of the plurality of electronic components adhered to the one side of the film; and removing the frame member from the stereolithography apparatus.”

Farnworth fails to disclose adhering a plurality of electronic components in fixed positions to one side of a film supported by a frame member; securing the frame member to a platform within a stereolithography apparatus. Rather, Farnworth discloses a die positioned on a sheet of material of a platform.

Therefore, it is respectfully submitted that the references fail to disclose each and every element of claim 11. Accordingly, it is respectfully submitted that the rejection to claim 11 should be withdrawn.

Each of claims 12-19 is allowable, among other reasons, for depending directly from independent claim 11, which is allowable.

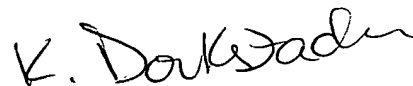
ENTRY OF AMENDMENTS

The amendments to claims 5 and 6 above should be entered by the Examiner because the amendments are supported by the as-filed specification and drawings and do not add any new matter to the application. The amendments merely grammatically clarify the claims.

CONCLUSION

Claims 5 through 19 are believed to be in condition for allowance, and an early notice thereof is respectfully solicited. Should the Examiner determine that additional issues remain which might be resolved by a telephone conference, he is respectfully invited to contact Applicant's undersigned attorney.

Respectfully submitted,



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